



JTW

S&H Form: (02/05)

REPLY/AMENDMENT FEE TRANSMITTAL	Attorney Docket No.	1572.1194	
	Application Number	10/706,033	
	Filing Date	November 13, 2003	
	First Named Inventor	Se-young JANG	
	Group Art Unit	1756	
AMOUNT ENCLOSED	0.00	Examiner Name	Nicole M. Barreca

FEE CALCULATION (fees effective 12/08/04)

CLAIMS AS AMENDED	Claims Remaining After Amendment	Highest Number Previously Paid For	Number Extra	Rate	Calculations
TOTAL CLAIMS	18	- 20 =	0	X \$ 50.00 =	\$ 0.00
INDEPENDENT CLAIMS	3	- 3 =	0	X \$ 200.00 =	0.00

Since an Official Action set an original due date of May 5, 2005, petition is hereby made for an extension to cover the date this reply is filed for which the requisite fee is enclosed (1 month (\$120)); (2 months (\$450)); (3 months (\$1,020)); (4 months (\$1,590)); (5 months (\$2,160)):

If Notice of Appeal is enclosed, add (\$500.00)

If Statutory Disclaimer under Rule 20(d) is enclosed, add fee (\$130.00)

Information Disclosure Statement (Rule 1.17(p)) (\$180.00)

Total of above Calculations =

\$ 0.00

Reduction by 50% for filing by small entity (37 CFR 1.9, 1.27 & 1.28)

TOTAL FEES DUE =

\$ 0.00

(1) If entry (1) is less than entry (2), entry (3) is "0".

(2) If entry (2) is less than 20, change entry (2) to "20".

(4) If entry (4) is less than entry (5), entry (6) is "0".

(5) If entry (5) is less than 3, change entry (5) to "3".

METHOD OF PAYMENT

- ☐ Check enclosed as payment.
- ☐ Charge "TOTAL FEES DUE" to the Deposit Account No. below.
- ☒ No payment is enclosed.

GENERAL AUTHORIZATION

- ☒ If the above-noted "AMOUNT ENCLOSED" is not correct, the Commissioner is hereby authorized to credit any overpayment or charge any additional fees necessary to:

Deposit Account No.

19-3935

Deposit Account Name

STAAS & HALSEY LLP

- ☒ The Commissioner is also authorized to credit any overpayments or charge any additional fees required under 37 CFR 1.16 (filing fees) or 37 CFR 1.17 (processing fees) during the prosecution of this application, including any related application(s) claiming benefit hereof pursuant to 35 USC § 120 (e.g., continuations/divisionals/CIPs under 37 CFR 1.53(b) and/or continuations/divisionals/CPAs under 37 CFR 1.53(d)) to maintain pendency hereof or of any such related application.

SUBMITTED BY: STAAS & HALSEY LLP

Typed Name	Michael J. Badagliacca	Reg. No.	39,099
Signature		Date	5-5-05

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Se-Young JANG

Serial No: 10/706,033

Group Art Unit: 1756

Confirmation No. 6029

Filed: November 13, 2003

Examiner: Nicole Barreca

For: METHOD OF FABRICATING LEAD-FREE SOLDER BUMPS

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

This is responsive to the Office Action mailed April 5, 2005, having a shortened period for response set to expire on May 5, 2005, the following remarks are provided.

I. Provisional Election of Claims Pursuant to 37 CFR §1.142

Applicants provisionally elect Group I (claims 1-6 and 14-18) in response to the preliminary restriction requirement set forth in the Office Action.

II. Applicants Traverse the Requirement

Insofar as Group II (claims 7-13) is concerned, it is believed that claims 7-13 are so closely related to elected claims 1-6 and 14-18 that they should remain in the same application. The elected claims 1-6 and 14-18 are directed to a method including, for example, providing a wafer having a protective layer and claims 7-13 are drawn to a lead-free solder bump of a semiconductor wafer, comprising a semiconductor wafer and a protective layer formed on the semiconductor wafer. There have been no references cited to show any necessity for requiring restriction. It is believed, moreover, that evaluation of all sets of claims would not provide an undue burden upon the Examiner at this time in comparison with the additional expense and delay to Applicants in having to protect the additional subject matter recited by the Group II claims by filing a divisional application.

MPEP §803 sets forth the criteria for restriction between patentably distinct inventions.

(A) indicates that the inventions must be independent (see MPEP §802.01, §806.04, §808.01) or distinct as claimed (see MPEP §806.05-806.05(i)); and (B) indicates that there must be a serious burden on the Examiner if restriction is required (see MPEP §803.02, §806.04(a)- §806.04(i), §808.01(a) and §808.02). The Examiner has not set forth why there would be a serious burden if restriction is required.

Even if the Examiner considers claims 7-13 to be a separate invention from claims 1-6 and 14-18, the Applicants respectfully request the Examiner to consider claims 7-13 (Group II) and claims 1-6 and 14-18 (Group I) together.

III. Conclusion

Upon review of references involved in this field of technology, when considering that the Group II claims are directed to a lead-free solder bump of a semiconductor wafer, and a protective layer formed on the semiconductor wafer and elected claims 1-6 and 14-18 are directed to a method including, for example, providing a wafer having a protective layer, and when all of the other various facts are taken into consideration, it is believed that upon reconsideration of the Examiner's initial restriction requirement, all of the pending claims should be examined in the subject application.

In view of the foregoing amendments, arguments and remarks, all claims are deemed to be allowable and this application is believed to be in condition for allowance.

If any further fees are required in connection with the filing of this Amendment, please charge the same to our deposit account number 19-3935.

Should any questions remain unresolved, the Examiner is requested to telephone Applicants' attorney.

Respectfully submitted,

STAAS & HALSEY LLP

Date: 1572.1194

By: 

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